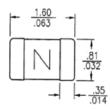
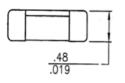
0603 Fast Acting SMD Fuses









Description

06H Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Features

AEC-Q200 Automotive Grade Certified Compatible with reflow and wave solder Excellent environmental integrity One time positive disconnect Lead Free and Halogen free material

Electrical Characteristics for Series

Applications

Power supplies

Consumer Electronicsii

Battery Chargers

Opening Time

4 Hour, Min

60Sec.,Max

Industrial Controllers

Agency Approvals.

	Safety Agency	Agency File Number	Ampere Range	% of Ampere Rating
	c RL ° us	E485357	250mA-8A	100%
				250%

Electrical Characteristic Specifications by Item

Lieuncal onaracteristic opecifications by item							
Part No	Rated Voltage DC	Rated Current (A)	Breaking Capacity (A) 1	Typical Cold. Resistance (mOhms) 2	Typical Voltage Drop (mV)	Typical Pre- Arcing I2t (A2Sec) 3	Alpha Mark
06H0250	63V	0.250	50A	3250	893	0.0004	D
06H0375		0.375	50A	1310	587	0.0009	E
06H0500		0.500	50A	1070	582	0.001	F
06H0750		0.750	50A	470	427	0.009	G
06H1100		1	50A	300	345	0.01	В
06H1150		1.5	50A	150	270	0.04	Н

* DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

* DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25degrees

* Typical Pre-arching I²t are measured at 10In Current

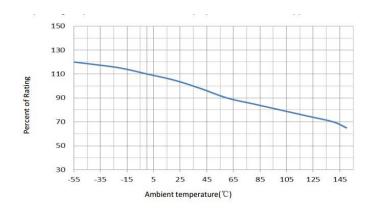
**No marking on fuse

Type 06H

0603 Fast Acting SMD Fuses

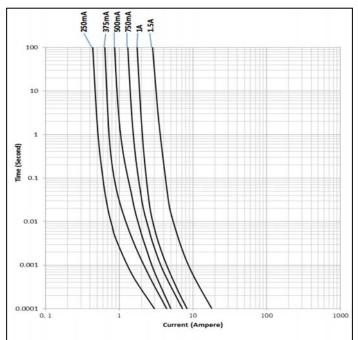
Temperature Re-rating Curve

- * Normal ambient temperature: 23±3°C
- * Operating temperature: -55 ~ +125℃, with proper correction factor applied



CHARGEN ROHS POFFEE

Average Time Current Curves



Soldering Method

■Wave solder

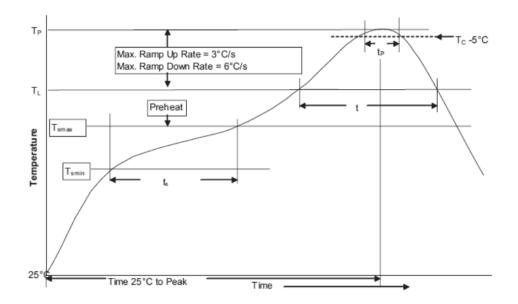
Reservoir temperature:260°C

Time in reservoir:10 seconds maximum

Infrared reflow

Temperature:260℃ Time: 30 seconds maximum

Solder Reflow Profile

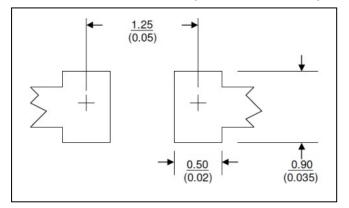


0603 Fast Acting SMD Fuses

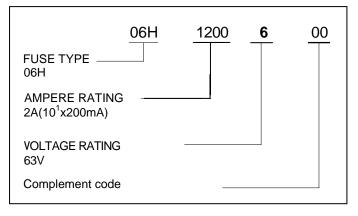


Profile Feature		Lead(Pb)free solder	
	Temperature min.(T _{smin})	150℃	
Preheat and soak	Temperature max.(T _{smax})	200 ℃	
	Time(T _{smin} to T _{smax})(ts)	60 - 120 Seconds	
Average ramp up rate T _{smax} to T _p		3℃ / Second Max.	
Liquidous temperature(TL)	217 ℃		
Time at liquidous(t _L)		60 – 150 Seconds	
Peak package body temperature(T _p)	260 ℃		
Time(T _p)within 5 $^{\circ}$ C of the specified cla	30 Seconds		
Average ramp-down rate(Tp to Tsmax)	6°C / Second Max.		
Time(25 [°] C to Peak Temperature)	8 Minutes Max.		

Mechanical Dimensions(Unit:mm/inches)



Ordering Information



Packaging

Packaging Option	Packaging Specification	Quantity	
06H	tape-and-reel	5000	